
HB56G236 Series, HB56G136 Series

HB56G236B/SB

8 MB FP DRAM SIMM

2-Mword $\times$ 36-bit, 1 k Refresh, 2-Bank Module

(4 pcs of 1 M $\times$ 16 and 4 pcs of 1 M $\times$ 2 Components)

HB56G136B/SB

4 MB FP DRAM SIMM

1-Mword $\times$ 36-bit, 1 k Refresh, 1-Bank Module

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HITACHI

ADE-203-702C (Z)

Rev.3.0

Nov. 1997

Description

The HB56G236 is a 2M $\times$ 36 dynamic RAM module, mounted 4 pieces of 16-Mbit DRAM (HM5118160) sealed in SOJ package and 4 pieces of 2-Mbit DRAM (HM512200) sealed in SOJ package. The HB56G136 is a 1M $\times$ 36 dynamic RAM module, mounted 2 pieces of 16-Mbit DRAM (HM5118160) sealed in SOJ package and 2 pieces of 2-Mbit DRAM (HM512200) sealed in SOJ package. An outline of the HB56G236, HB56G136 is 72-pin single in-line package. Therefore, the HB56G236, HB56G136 make high density mounting possible without surface mount technology. The HB56G236, HB56G136 provide common data inputs and outputs. Decoupling capacitors are mounted on the module board.

Features

- 72-pin single in-line package
 - Outline: 107.95 mm (Length) $\times$ 25.40 mm (Height) $\times$ 9.14/5.28 mm (Thickness)
 - Lead pitch: 1.27 mm
- Single 5 V ($\pm 5\%$) supply
- High speed
 - Access time: $t_{\text{RAC}} = 60 / 70\text{ns}$ (max)

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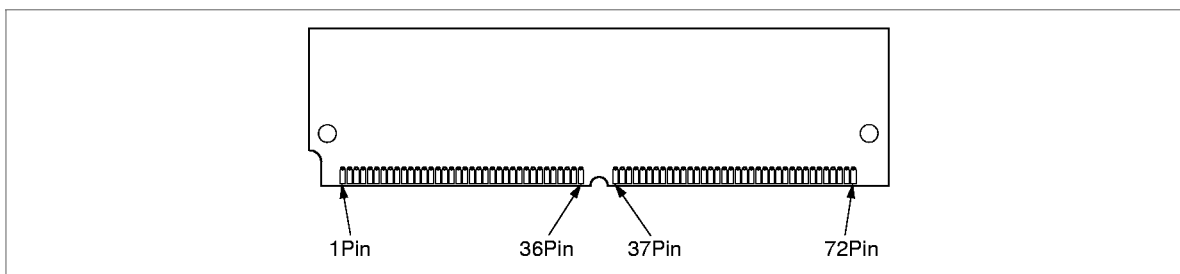
- Low power dissipation
 - Active mode: 2.73/2.42 W (max) (HB56G236 Series)
2.63/2.31 W (max) (HB56G136 Series)
 - Standby mode (TTL): 84 mW (max) (HB56G236 Series)
(TTL): 42 mW (max) (HB56G136 Series)
(CMOS): 5.25 mW (max) (L-version) (HB56G236 Series)
(CMOS): 2.63 mW (max) (L-version) (HB56G136 Series)
- Fast page mode capability
- Refresh period
 - 1024 refresh cycles: 16 ms
128 ms (L-version)
- 3 variations of refresh
 - $\overline{\text{RAS}}$ -only refresh
 - $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh
 - Hidden refresh
- TTL compatible

Ordering Information

Type No.	Access time	Package	Contact pad
HB56G236B-6	60 ns	72-pin SIP socket type	Gold
HB56G236B-7	70 ns		
HB56G236B-6L	60 ns		
HB56G236B-7L	70 ns		
HB56G136B-6	60 ns	72-pin SIP socket type	Solder
HB56G136B-7	70 ns		
HB56G136B-6L	60 ns		
HB56G136B-7L	70 ns		
HB56G236SB-6	60 ns	72-pin SIP socket type	Solder
HB56G236SB-7	70 ns		
HB56G236SB-6L	60 ns		
HB56G236SB-7L	70 ns		
HB56G136SB-6	60 ns	72-pin SIP socket type	Solder
HB56G136SB-7	70 ns		
HB56G136SB-6L	60 ns		
HB56G136SB-7L	70 ns		

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Pin Arrangement



Pin No.	Pin name	Pin No.	Pin name	Pin No.	Pin name	Pin No.	Pin name
1	V _{SS}	19	NC	37	DQ17	55	DQ12
2	DQ0	20	DQ4	38	DQ35	56	DQ30
3	DQ18	21	DQ22	39	V _{SS}	57	DQ13
4	DQ1	22	DQ5	40	$\overline{\text{CAS0}}$	58	DQ31
5	DQ19	23	DQ23	41	$\overline{\text{CAS2}}$	59	V _{CC}
6	DQ2	24	DQ6	42	$\overline{\text{CAS3}}$	60	DQ32
7	DQ20	25	DQ24	43	$\overline{\text{CAS1}}$	61	DQ14
8	DQ3	26	DQ7	44	$\overline{\text{RAS0}}$	62	DQ33
9	DQ21	27	DQ25	45	$\overline{\text{RAS1}}$ (NC)* ²	63	DQ15
10	V _{CC}	28	A7	46	NC	64	DQ34
11	NC	29	NC	47	$\overline{\text{WE}}$	65	DQ16
12	A0	30	V _{CC}	48	NC	66	NC
13	A1	31	A8	49	DQ9	67	PD1
14	A2	32	A9	50	DQ27	68	PD2
15	A3	33	$\overline{\text{RAS3}}$ (NC)* ¹	51	DQ10	69	PD3
16	A4	34	$\overline{\text{RAS2}}$	52	DQ28	70	PD4
17	A5	35	DQ26	53	DQ11	71	NC
18	A6	36	DQ8	54	DQ29	72	V _{SS}

Notes: 1. $\overline{\text{RAS3}}$: HB56G236, NC: HB56G136

2. $\overline{\text{RAS1}}$: HB56G236, NC: HB56G136

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Pin Description

Pin name	Function
A0 to A9	Address inputs: - Row address: A0 to A9 - Column address: A0 to A9 - Refresh address: A0 to A9
DQ0 to DQ35	Data-in/Data-out
$\overline{\text{CAS0}}$ to $\overline{\text{CAS3}}$	Column address strobe
$\overline{\text{RAS0}}$ to $\overline{\text{RAS3}}$	Row address strobe
$\overline{\text{WE}}$	Read/Write enable
V_{CC}	Power supply
V_{SS}	Ground
PD1 to PD4	Presence detect pin
NC	No connection

Presence Detect Pin Arrangement (HB56G236)

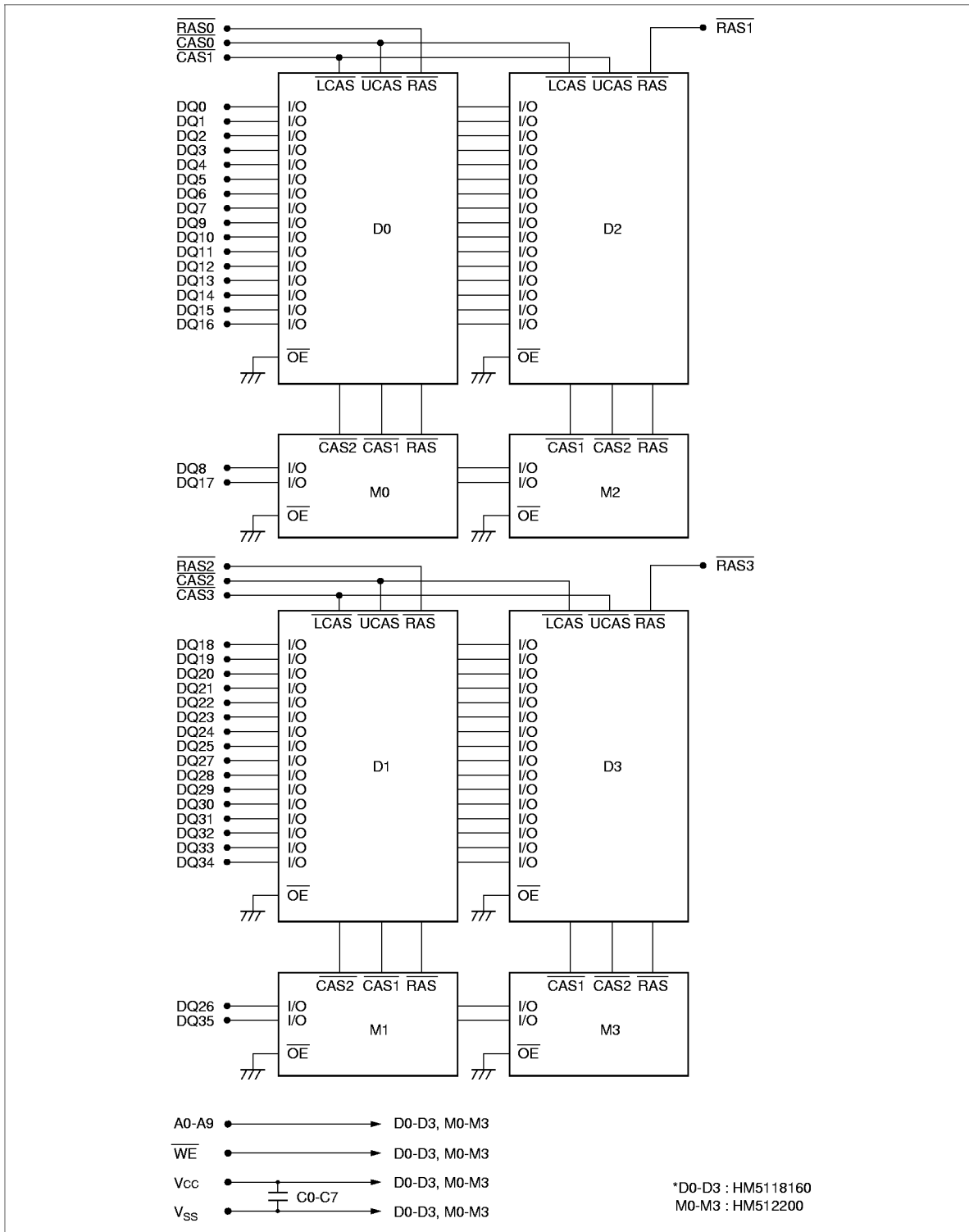
Pin No.	Pin name	Function	
		60 ns	70 ns
67	PD1	NC	NC
68	PD2	NC	NC
69	PD3	NC	V_{SS}
70	PD4	NC	NC

Presence Detect Pin Arrangement (HB56G136)

Pin No.	Pin name	Function	
		60 ns	70 ns
67	PD1	V_{SS}	V_{SS}
68	PD2	V_{SS}	V_{SS}
69	PD3	NC	V_{SS}
70	PD4	NC	NC

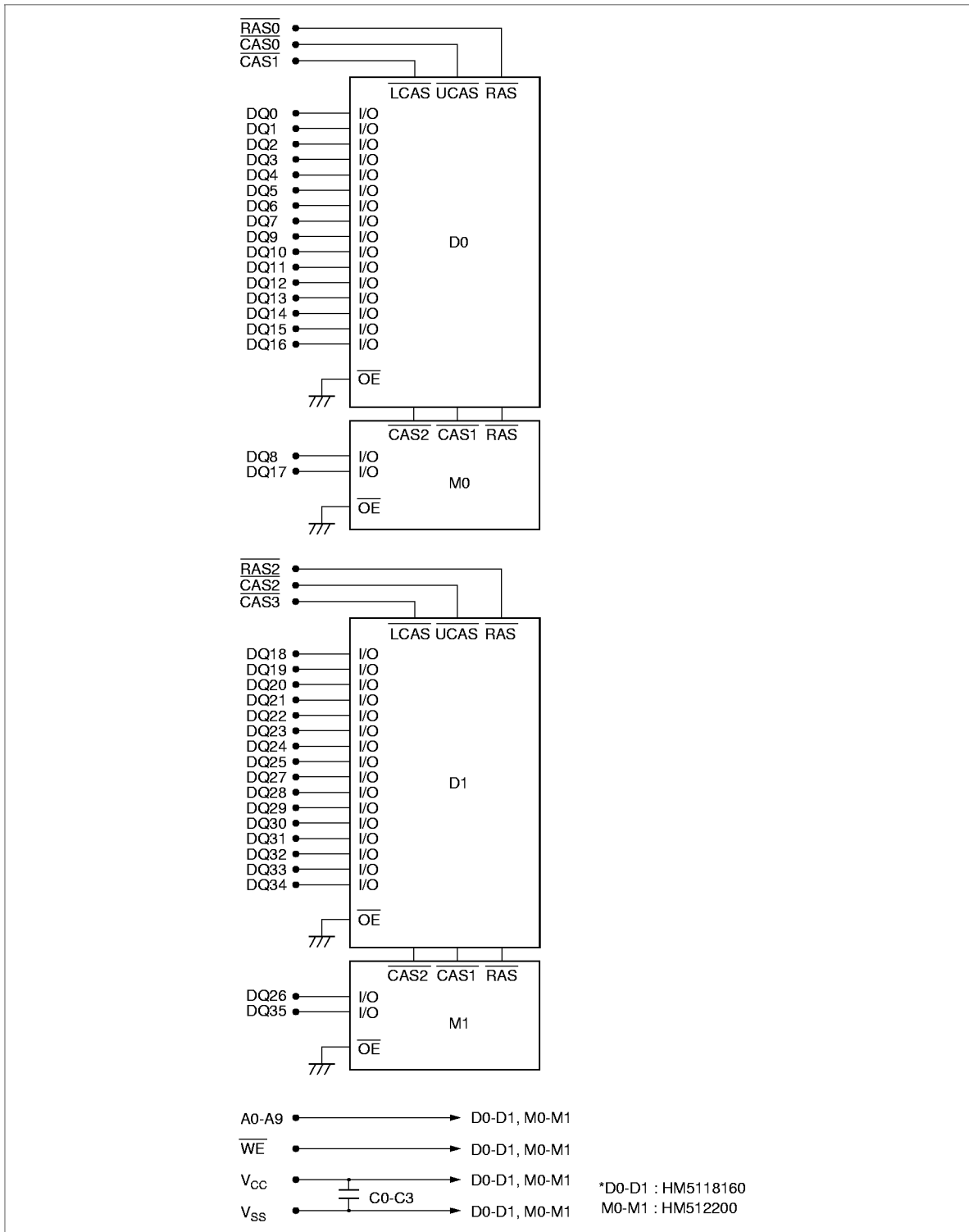
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Block Diagram (HB56G236)



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Block Diagram (HB56G136)



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Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Voltage on any pin relative to V_{SS}	V_T	-1.0 to +7.0	V
Supply voltage relative to V_{SS}	V_{CC}	-1.0 to +7.0	V
Short circuit output current	I_{out}	50	mA
Power dissipation	P_t	4	W
Operating temperature	T_{opr}	0 to +70	°C
Storage temperature	T_{stg}	-55 to +125	°C

Recommended DC Operating Conditions ($T_a = 0$ to 70°C)

Parameter	Symbol	Min	Typ	Max	Unit	Note
Supply voltage	V_{SS}	0	0	0	V	
	V_{CC}	4.75	5.0	5.25	V	1
Input high voltage	V_{IH}	2.4	—	5.5	V	1
Input low voltage	V_{IL}	-1.0	—	0.8	V	1

Note: 1. All voltage referred to V_{SS} .

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DC Characteristics ($T_a = 0 \text{ to } 70^\circ\text{C}$, $V_{CC} = 5 \text{ V} \pm 5\%$, $V_{SS} = 0 \text{ V}$) (HB56G236)

Parameter	Symbol	60 ns		70 ns		Unit	Test conditions	Notes
		Min	Max	Min	Max			
Operating current	I_{CC1}	—	520	—	460	mA	$t_{RC} = \min$	1, 2
Standby current	I_{CC2}	—	16	—	16	mA	TTL interface, $\overline{RAS}, \overline{CAS} = V_{IH}$, Dout = High-Z	
		—	8	—	8	mA	CMOS interface, $\overline{RAS}, \overline{CAS} \geq V_{CC} - 0.2 \text{ V}$, Dout = High-Z	
Standby current (L-version)	I_{CC2}	—	1	—	1	mA	CMOS interface, $\overline{RAS}, \overline{CAS} \geq V_{CC} - 0.2 \text{ V}$, Dout = High-Z	
$\overline{RAS}$ -only refresh current	I_{CC3}	—	520	—	460	mA	$t_{RC} = \min$	2
Standby current	I_{CC5}	—	40	—	40	mA	$\overline{RAS} = V_{IH}$, $\overline{CAS} = V_{IL}$, Dout = enable	1
$\overline{CAS}$ -before- $\overline{RAS}$ refresh current	I_{CC6}	—	520	—	460	mA	$t_{RC} = \min$	
Fast page mode current	I_{CC7}	—	510	—	450	mA	$t_{PC} = \min$	1, 3
Battery backup current (Standby with CBR refresh) (L-version)	I_{CC10}	—	3.2	—	3.2	mA	CMOS interface, Dout = High-Z, CBR refresh: $t_{RC} = 125 \mu\text{s}$, $t_{RAS} \leq 0.3 \mu\text{s}$	4
Input leakage current	I_{LI}	-10	10	-10	10	μA	$0 \text{ V} \leq V_{in} \leq 5.5 \text{ V}$	
Output leakage current	I_{LO}	-10	10	-10	10	μA	$0 \text{ V} \leq V_{out} \leq 5.5 \text{ V}$, Dout = disable	
Output high voltage	V_{OH}	2.4	V_{CC}	2.4	V_{CC}	V	High Iout = -5 mA	
Output low voltage	V_{OL}	0	0.4	0	0.4	V	Low Iout = 4.2 mA	

Notes: 1. I_{CC} depends on output load condition when the device is selected, I_{CC} max is specified at the output open condition.

2. Address can be changed once or less while $\overline{RAS} = V_{IL}$.

3. Address can be changed once or less while $\overline{CAS} = V_{IH}$.

4. $V_{IH} \geq V_{CC} - 0.2 \text{ V}$, $0 \text{ V} \leq V_{IL} \leq 0.2 \text{ V}$.

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DC Characteristics ($T_a = 0$ to 70°C , $V_{CC} = 5\text{ V} \pm 5\%$, $V_{SS} = 0\text{ V}$) (HB56G136)

Parameter	Symbol	60 ns		70 ns		Unit	Test conditions	Notes
		Min	Max	Min	Max			
Operating current	I_{CC1}	—	500	—	440	mA	$t_{RC} = \min$	1, 2
Standby current	I_{CC2}	—	8	—	8	mA	TTL interface, $\overline{RAS}, \overline{CAS} = V_{IH}$, Dout = High-Z	
		—	4	—	4	mA	CMOS interface, $\overline{RAS}, \overline{CAS} \geq V_{CC} - 0.2\text{ V}$, Dout = High-Z	
Standby current (L-version)	I_{CC2}	—	0.5	—	0.5	mA	CMOS interface, $\overline{RAS}, \overline{CAS} \geq V_{CC} - 0.2\text{ V}$, Dout = High-Z	
$\overline{RAS}$ -only refresh current	I_{CC3}	—	500	—	440	mA	$t_{RC} = \min$	2
Standby current	I_{CC5}	—	20	—	20	mA	$\overline{RAS} = V_{IH}$, $\overline{CAS} = V_{IL}$, Dout = enable	1
$\overline{CAS}$ -before- $\overline{RAS}$ refresh current	I_{CC6}	—	500	—	440	mA	$t_{RC} = \min$	
Fast page mode current	I_{CC7}	—	490	—	430	mA	$t_{PC} = \min$	1, 3
Battery backup current (Standby with CBR refresh) (L-version)	I_{CC10}	—	1.6	—	1.6	mA	CMOS interface, Dout = High-Z, CBR refresh: $t_{RC} = 125\text{ }\mu\text{s}$, $t_{RAS} \leq 0.3\text{ }\mu\text{s}$	4
Input leakage current	I_{LI}	-10	10	-10	10	μA	$0\text{ V} \leq V_{in} \leq 5.5\text{ V}$	
Output leakage current	I_{LO}	-10	10	-10	10	μA	$0\text{ V} \leq V_{out} \leq 5.5\text{ V}$, Dout = disable	
Output high voltage	V_{OH}	2.4	V_{CC}	2.4	V_{CC}	V	High Iout = -5 mA	
Output low voltage	V_{OL}	0	0.4	0	0.4	V	Low Iout = 4.2 mA	

Notes: 1. I_{CC} depends on output load condition when the device is selected, I_{CC} max is specified at the output open condition.

2. Address can be changed once or less while $\overline{RAS} = V_{IL}$.

3. Address can be changed once or less while $\overline{CAS} = V_{IH}$.

4. $V_{IH} \geq V_{CC} - 0.2\text{ V}$, $0\text{ V} \leq V_{IL} \leq 0.2\text{ V}$.

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Capacitance (Ta = 25°C, V_{CC} = 5 V ± 5%) (HB56G236)

Parameter	Symbol	Typ	Max	Unit	Notes
Input capacitance (Address)	C _{I1}	—	60	pF	1
Input capacitance ($\overline{WE}$)	C _{I2}	—	76	pF	1
Input capacitance ($\overline{RAS}$)	C _{I3}	—	34	pF	1
Input capacitance ($\overline{CAS}$)	C _{I4}	—	48	pF	1
I/O capacitance (DQ)	C _{I/O}	—	34	pF	1, 2

Notes: 1. Capacitance measured with Boonton Meter or effective capacitance measuring method.
 2. $\overline{CAS} = V_{IH}$ to disable Dout.

Capacitance (Ta = 25°C, V_{CC} = 5 V ± 5%) (HB56G136)

Parameter	Symbol	Typ	Max	Unit	Notes
Input capacitance (Address)	C _{I1}	—	40	pF	1
Input capacitance ($\overline{WE}$)	C _{I2}	—	48	pF	1
Input capacitance ($\overline{RAS}$)	C _{I3}	—	34	pF	1
Input capacitance ($\overline{CAS}$)	C _{I4}	—	34	pF	1
I/O capacitance (DQ)	C _{I/O}	—	27	pF	1, 2

Notes: 1. Capacitance measured with Boonton Meter or effective capacitance measuring method.
 2. $\overline{CAS} = V_{IH}$ to disable Dout.

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AC Characteristics ($T_a = 0 \text{ to } 70^\circ\text{C}$, $V_{CC} = 5 \text{ V} \pm 5\%$, $V_{SS} = 0 \text{ V}$) *¹, *², *¹⁷

Test Conditions

- Input rise and fall times: 5 ns
- Input timing reference levels: 0.8 V, 2.4 V
- Output timing reference levels: 0.4 V, 2.4 V
- Output load: 2 TTL gate + C_L (100 pF) (Including scope and jig)

Read, Write, and Refresh Cycles (Common parameters)

Parameter	Symbol	60 ns		70 ns		Unit	Notes
		Min	Max	Min	Max		
Random read or write cycle time	t_{RC}	110	—	130	—	ns	
$\overline{RAS}$ precharge time	t_{RP}	40	—	50	—	ns	
$\overline{CAS}$ precharge time	t_{CP}	10	—	10	—	ns	
$\overline{RAS}$ pulse width	t_{RAS}	60	10000	70	10000	ns	
$\overline{CAS}$ pulse width	t_{CAS}	15	10000	20	10000	ns	
Row address setup time	t_{ASR}	0	—	0	—	ns	
Row address hold time	t_{RAH}	10	—	10	—	ns	
Column address setup time	t_{ASC}	0	—	0	—	ns	
Column address hold time	t_{CAH}	15	—	15	—	ns	
$\overline{RAS}$ to $\overline{CAS}$ delay time	t_{RCD}	20	45	20	50	ns	3
$\overline{RAS}$ to column address delay time	t_{RAD}	15	30	15	35	ns	4
$\overline{RAS}$ hold time	t_{RSH}	15	—	20	—	ns	
$\overline{CAS}$ hold time	t_{CSH}	60	—	70	—	ns	
$\overline{CAS}$ to $\overline{RAS}$ precharge time	t_{CRP}	10	—	10	—	ns	
$\overline{CAS}$ delay time from D_{in}	t_{DZC}	0	—	0	—	ns	
Transition time (rise and fall)	t_T	3	50	3	50	ns	5
Refresh period (1,024 cycles)	t_{REF}	—	16	—	16	ms	
Refresh period (1,024 cycles) (L-version)	t_{REF}	—	128	—	128	ms	

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Read Cycle

Parameter	Symbol	60 ns		70 ns		Unit	Notes
		Min	Max	Min	Max		
Access time from $\overline{\text{RAS}}$	t_{RAC}	—	60	—	70	ns	6, 7
Access time from $\overline{\text{CAS}}$	t_{CAC}	—	15	—	20	ns	7, 8, 15
Access time from address	t_{AA}	—	30	—	35	ns	7, 9, 15
Read command setup time	t_{RCS}	0	—	0	—	ns	
Read command hold time to $\overline{\text{CAS}}$	t_{RCH}	0	—	0	—	ns	10
Read command hold time to $\overline{\text{RAS}}$	t_{RRH}	5	—	5	—	ns	10
Column address to $\overline{\text{RAS}}$ lead time	t_{RAL}	30	—	35	—	ns	
Column address to $\overline{\text{CAS}}$ lead time	t_{CAL}	30	—	35	—	ns	
$\overline{\text{CAS}}$ to output in low-Z	t_{CLZ}	0	—	0	—	ns	
Output data hold time	t_{OH}	3	—	3	—	ns	
Output buffer turn-off time	t_{OFF}	—	15	—	20	ns	11
$\overline{\text{CAS}}$ to Din delay time	t_{CDD}	15	—	20	—	ns	

Write Cycle

Parameter	Symbol	60 ns		70 ns		Unit	Notes
		Min	Max	Min	Max		
Write command setup time	t_{WCS}	0	—	0	—	ns	12
Write command hold time	t_{WCH}	15	—	15	—	ns	
Write command pulse width	t_{WCP}	10	—	10	—	ns	
Data-in setup time	t_{DS}	0	—	0	—	ns	13
Data-in hold time	t_{DH}	15	—	15	—	ns	13

Refresh Cycle

Parameter	Symbol	60 ns		70 ns		Unit	Notes
		Min	Max	Min	Max		
$\overline{\text{CAS}}$ setup time (CBR refresh cycle)	t_{CSR}	10	—	10	—	ns	
$\overline{\text{CAS}}$ hold time (CBR refresh cycle)	t_{CHR}	10	—	10	—	ns	
$\overline{\text{WE}}$ setup time (CBR refresh cycle)	t_{WRP}	0	—	0	—	ns	
$\overline{\text{WE}}$ hold time (CBR refresh cycle)	t_{WRH}	10	—	10	—	ns	
$\overline{\text{RAS}}$ precharge to $\overline{\text{CAS}}$ hold time	t_{RPC}	10	—	10	—	ns	

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Fast Page Mode Cycle

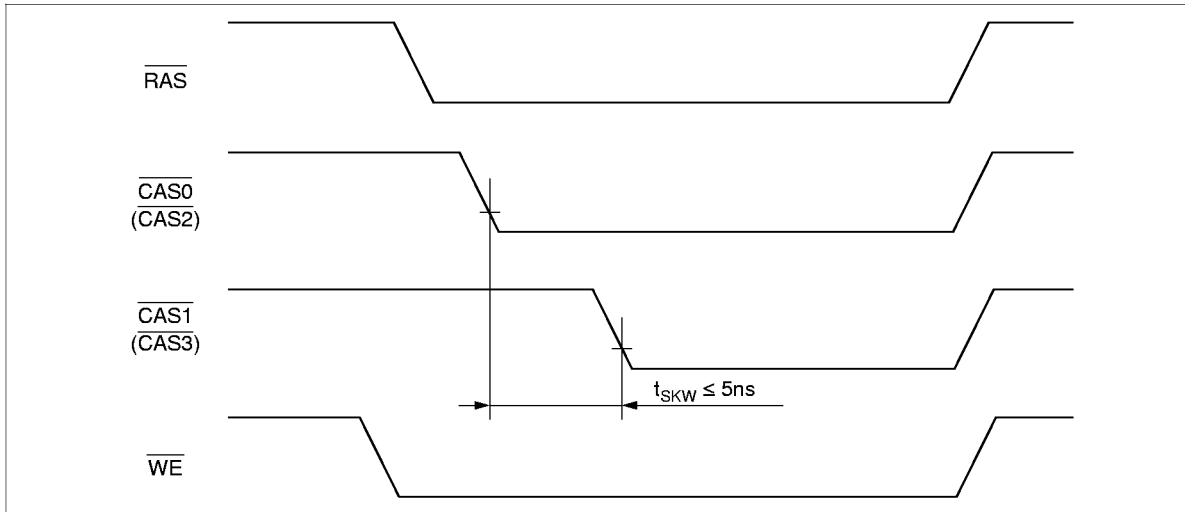
Parameter	Symbol	60 ns		70 ns		Unit	Notes
		Min	Max	Min	Max		
Fast page mode cycle time	t_{PC}	40	—	45	—	ns	
Fast page mode $\overline{RAS}$ pulse width	t_{RASP}	—	100000	—	100000	ns	14
Access time from $\overline{CAS}$ precharge	t_{CPA}	—	35	—	40	ns	7, 15
$\overline{RAS}$ hold time from $\overline{CAS}$ precharge	t_{CPRH}	35	—	40	—	ns	

- Notes:
1. AC measurements assume $t_T = 5$ ns.
 2. An initial pause of 200 μ s is required after power up followed by a minimum of eight initialization cycles (any combination of cycles containing $\overline{RAS}$ -only refresh cycle or $\overline{CAS}$ -before- $\overline{RAS}$ refresh). If the internal refresh counter is used, a minimum of eight $\overline{CAS}$ -before- $\overline{RAS}$ refresh cycles are required.
 3. Operation with the t_{RCD} (max) limit insures that t_{RAC} (max) can be met, t_{RCD} (max) is specified as a reference point only; if t_{RCD} is greater than the specified t_{RCD} (max) limit, then access time is controlled exclusively by t_{CAC} .
 4. Operation with the t_{RAD} (max) limit insures that t_{RAC} (max) can be met, t_{RAD} (max) is specified as a reference point only; if t_{RAD} is greater than the specified t_{RAD} (max) limit, then access time is controlled exclusively by t_{AA} .
 5. V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals. Also, transition times are measured between V_{IH} (min) and V_{IL} (max).
 6. Assumes that $t_{RCD} \leq t_{RCD}$ (max) and $t_{RAD} \leq t_{RAD}$ (max). If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} exceeds the value shown.
 7. Measured with a load circuit equivalent to 2 TTL loads and 100 pF.
 8. Assumes that $t_{RCD} \geq t_{RCD}$ (max) and $t_{RCD} + t_{CAC}$ (max) $\geq t_{RAD} + t_{AA}$ (max).
 9. Assumes that $t_{RAD} \geq t_{RAD}$ (max) and $t_{RCD} + t_{CAC}$ (max) $\leq t_{RAD} + t_{AA}$ (max).
 10. Either t_{RCH} or t_{RRH} must be satisfied for a read cycles.
 11. t_{OFF} (max) defines the time at which the outputs achieve the open circuit condition and are not referred to output voltage levels.
 12. Early write cycle only ($t_{WCS} \geq t_{WCS}$ (min)).
 13. These parameters are referred to $\overline{CAS}$ leading edge in early write cycles.
 14. t_{RASP} defines $\overline{RAS}$ pulse width in Fast page mode cycles.
 15. Access time is determined by the longest among t_{AA} , t_{CAC} and t_{CPA} .
 16. When output buffers are enabled once, sustain the low impedance state until valid data is obtained. When output buffer is turned on and off within a very short time, generally it causes large V_{CC}/V_{SS} line noise, which causes to degrade V_{IH} min./ V_{IL} max level.
 17. All the V_{CC} and V_{SS} pins shall be supplied with the same voltages.
 18. XXX: H or L (H: V_{IH} (min) $\leq V_{IN} \leq V_{IH}$ (max), L: V_{IL} (min) $\leq V_{IN} \leq V_{IL}$ (max))
 // : Invalid Dout
 When the address, clock and input pins are not described on timing waveforms, their pins must be applied V_{IH} or V_{IL} .

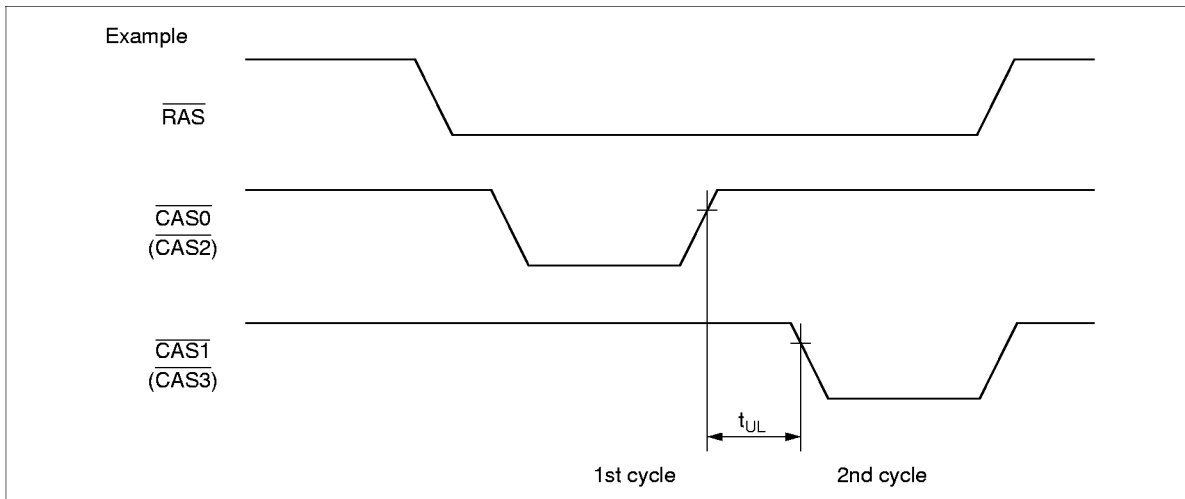
HB56G236 Series, HB56G136 Series

Notes concerning $2\overline{\text{CAS}}$ control

1. In one memory cycle, activate both of $2\overline{\text{CAS}}$ s ($\overline{\text{CAS0}}$ and $\overline{\text{CAS1}}$ (or $\overline{\text{CAS2}}$ and $\overline{\text{CAS3}}$)) or only one of them or neither of them.
2. To activate both of $2\overline{\text{CAS}}$ s in an early write cycle or a page mode early write cycle, please keep t_{SKW} (skew between $\overline{\text{CAS0}}$ and $\overline{\text{CAS1}}$ (or $\overline{\text{CAS2}}$ and $\overline{\text{CAS3}}$)) 5 ns or less.

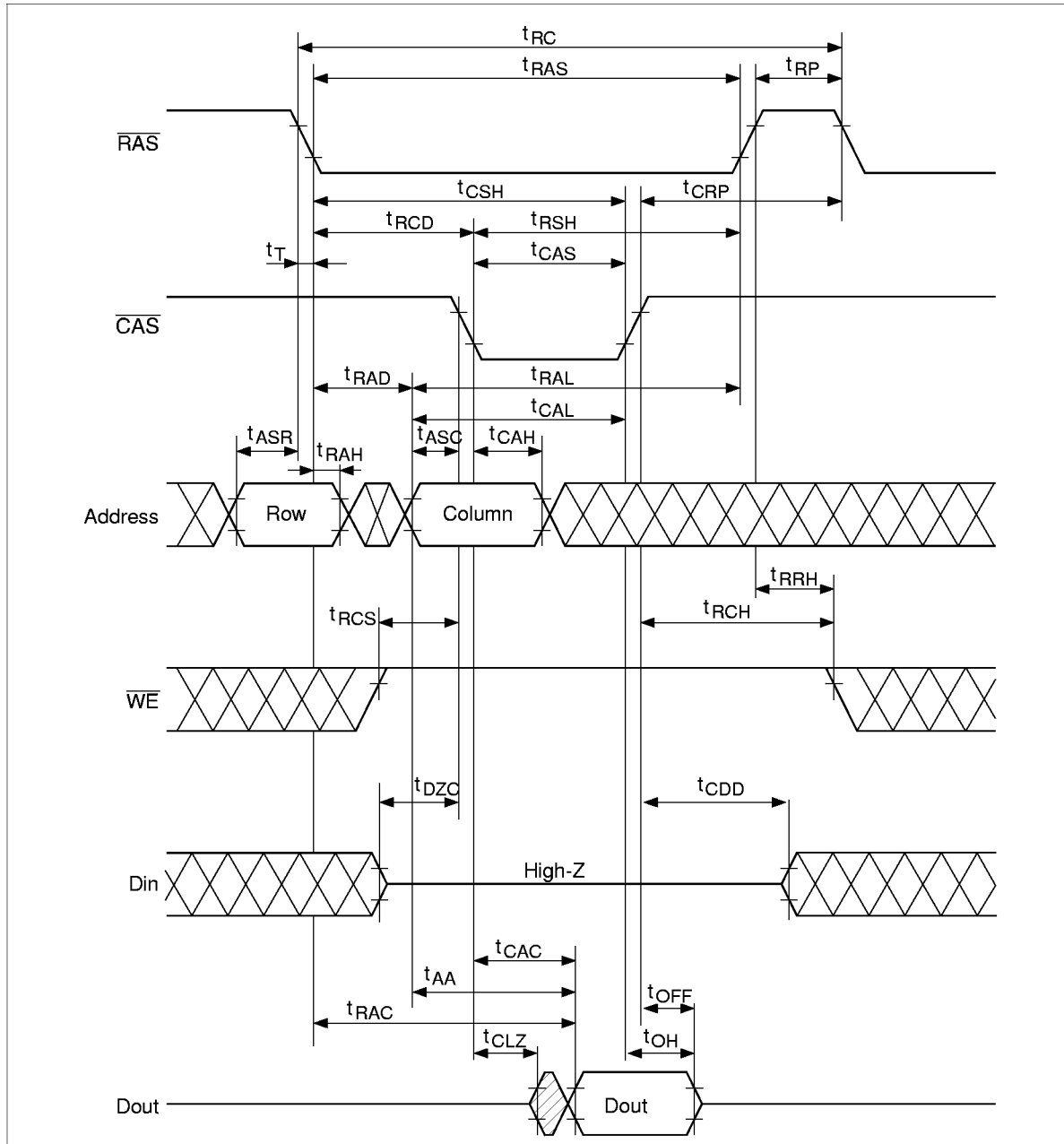


3. If the different $\overline{\text{CAS}}$ s are activated in the consecutive page cycles, t_{UL} the period that both $\overline{\text{CAS}}$ s are high, should be keep $t_{\text{CP spec}}$ ($t_{\text{CP min}} \leq t_{\text{UL}}$).



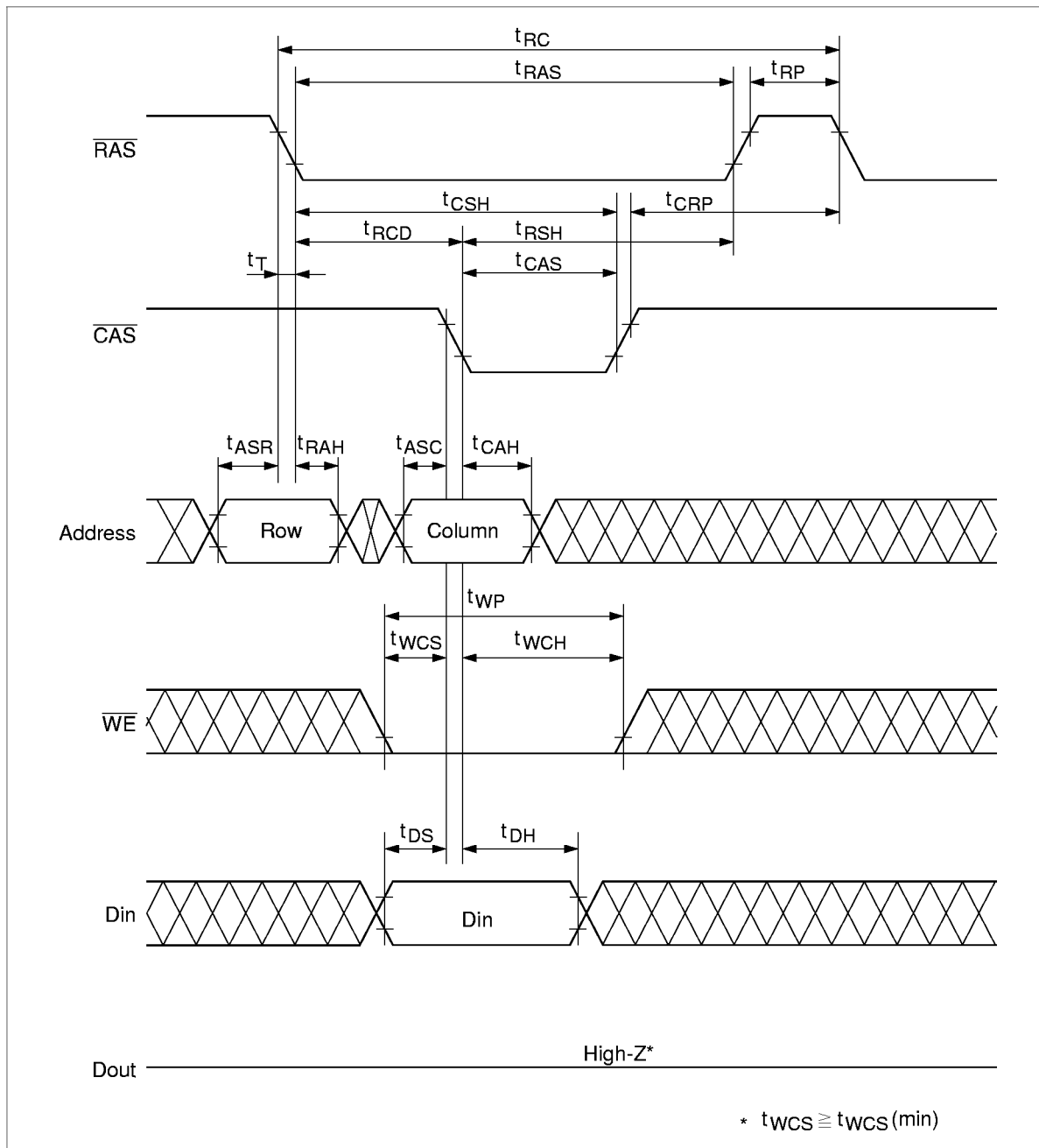
Timing Waveforms*¹⁸

Read Cycle



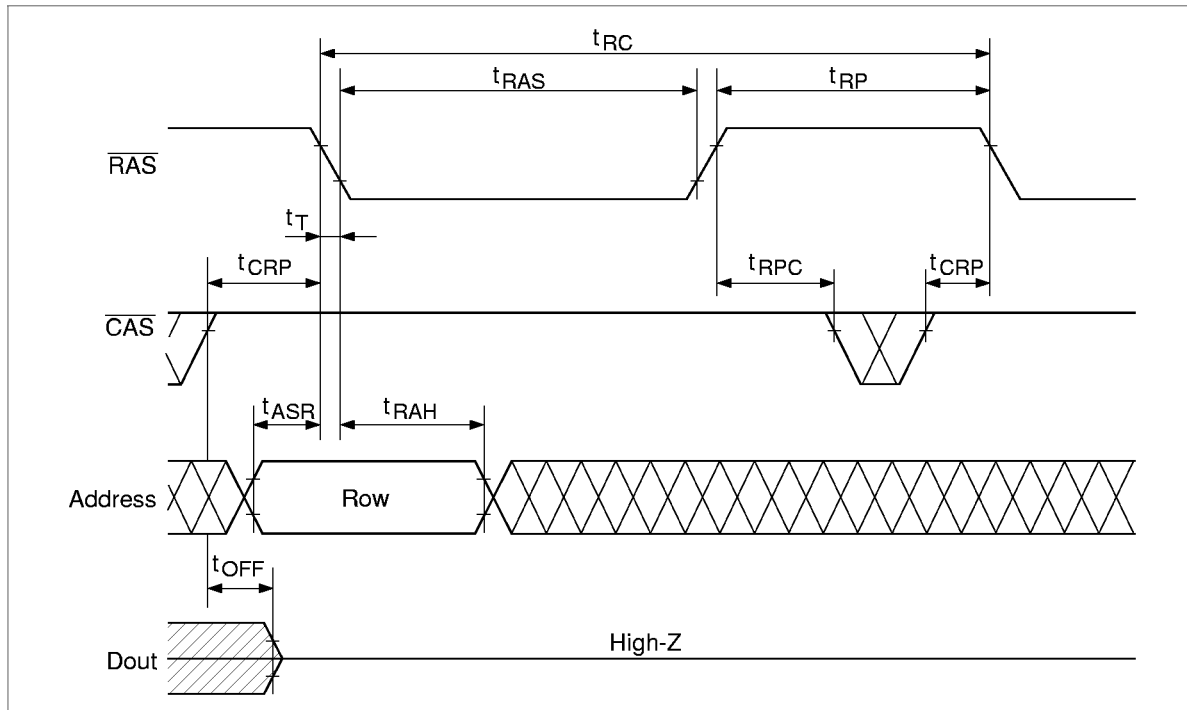
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Early Write Cycle



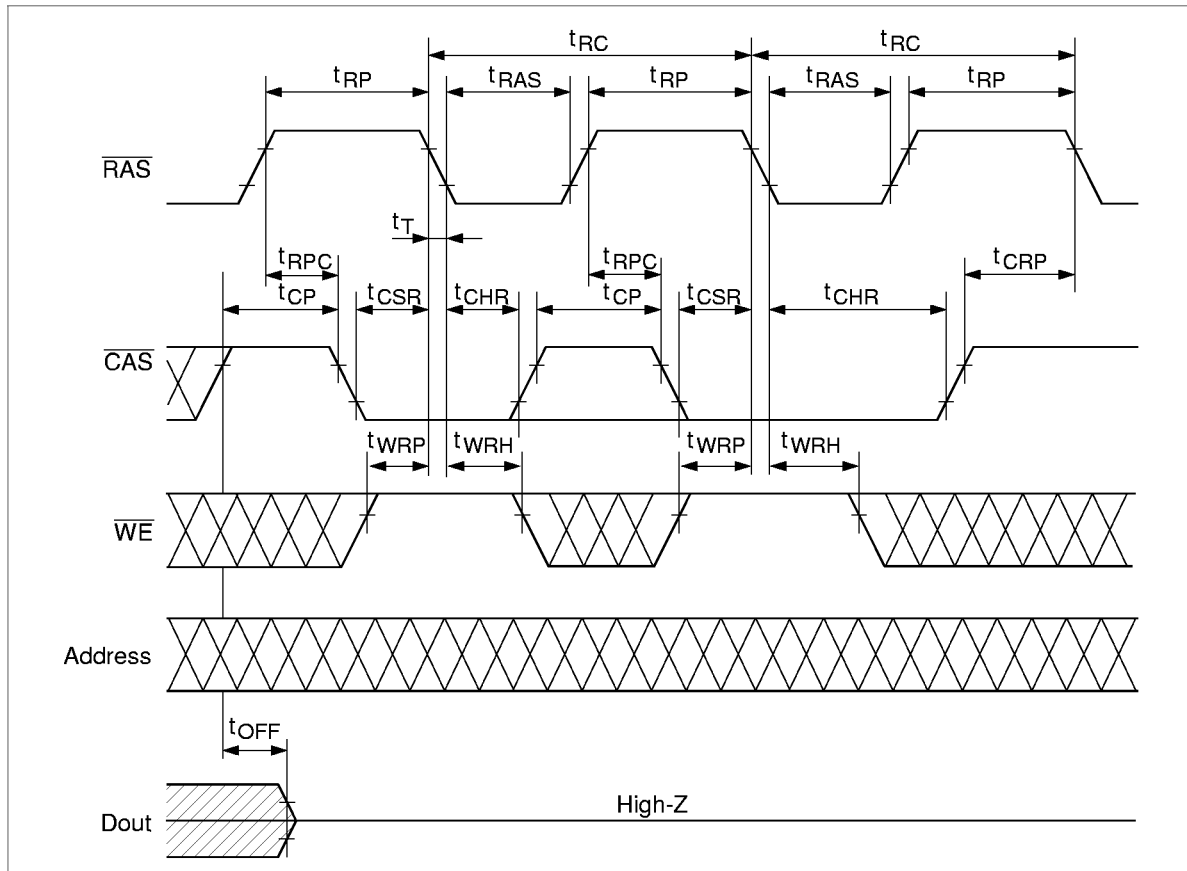
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$\overline{\text{RAS}}$ -Only Refresh Cycle



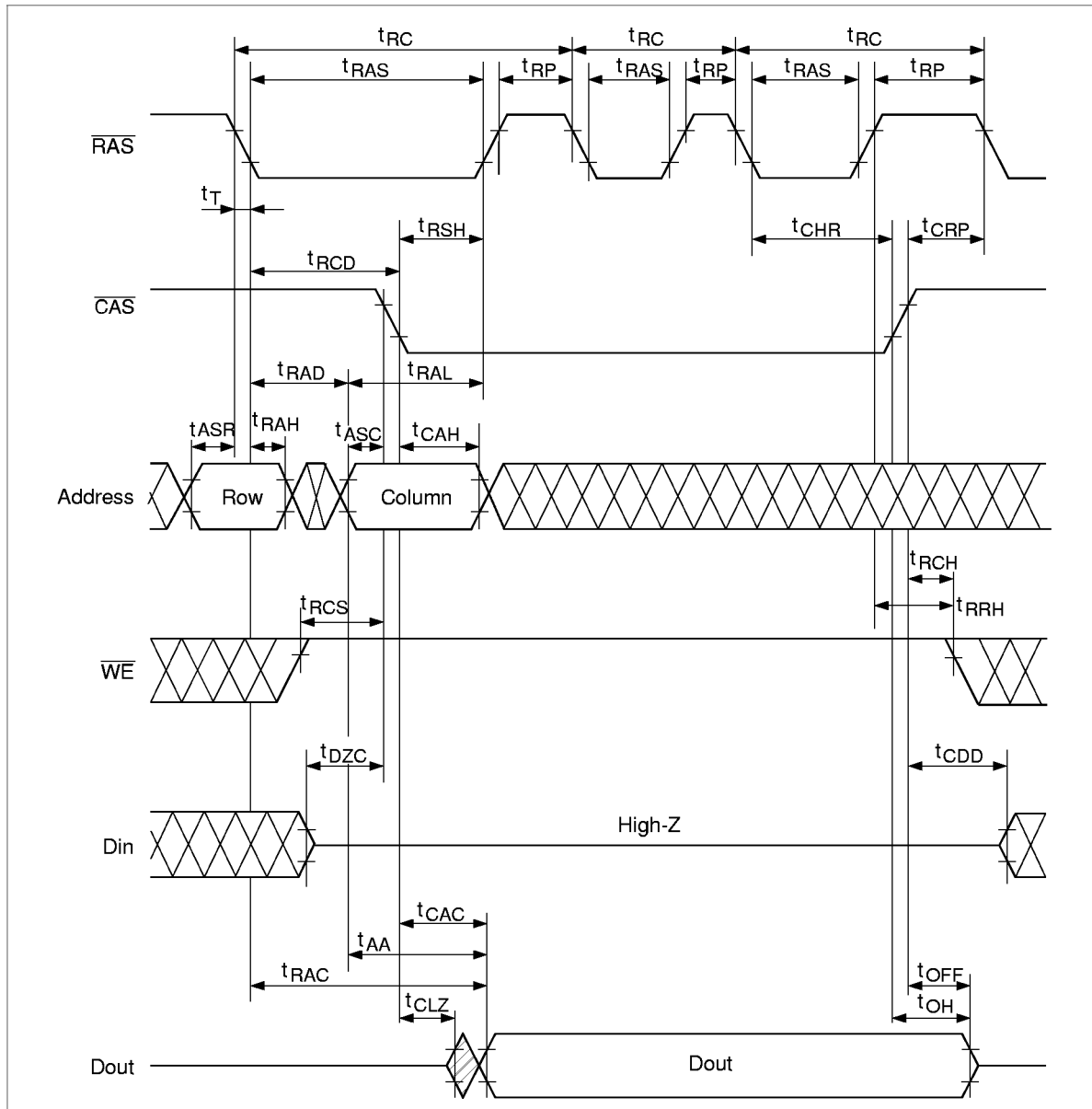
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$\overline{\text{CAS}}$ -Before- $\overline{\text{RAS}}$ Refresh Cycle



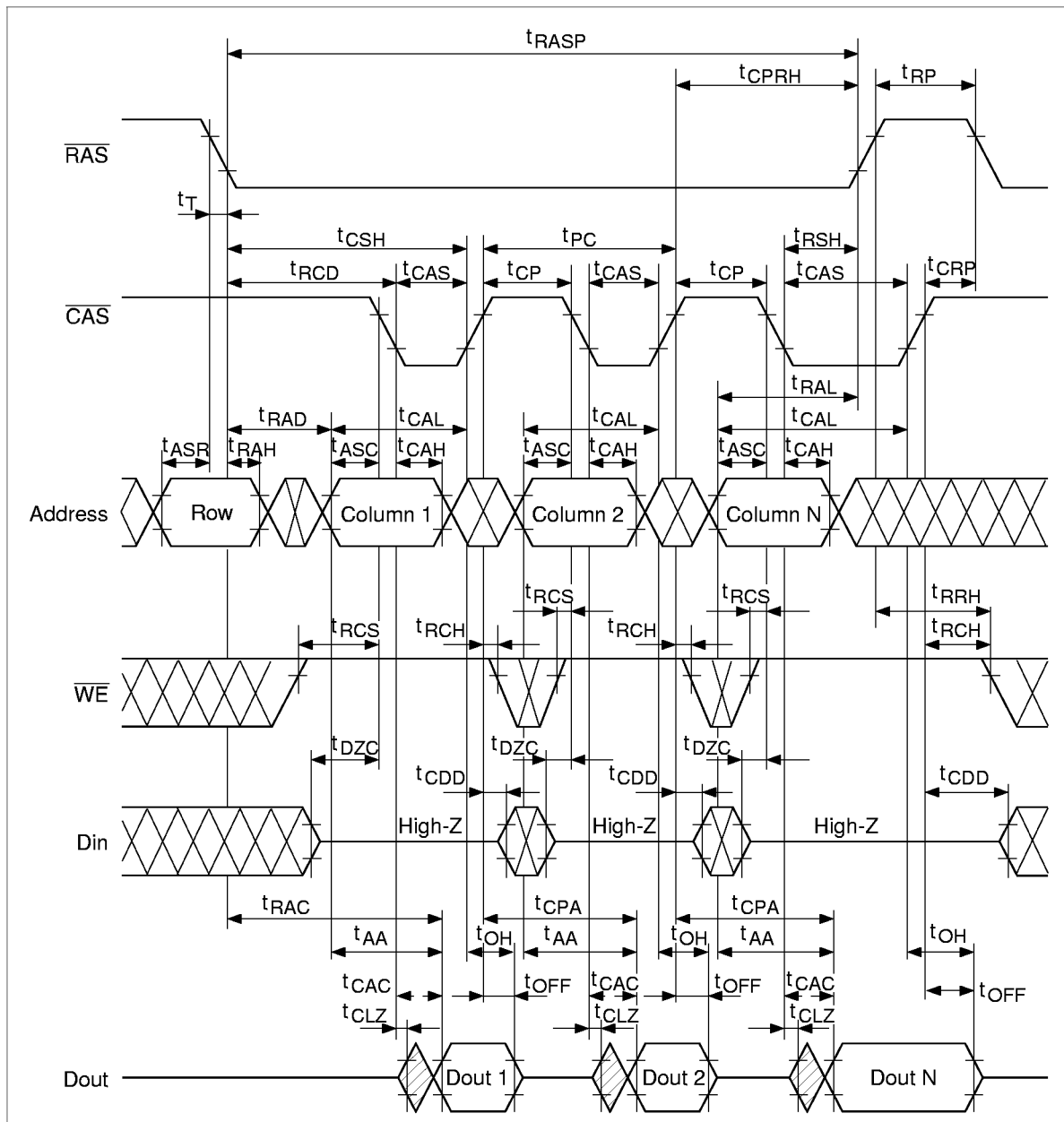
HB56G236 Series, HB56G136 Series

Hidden Refresh Cycle

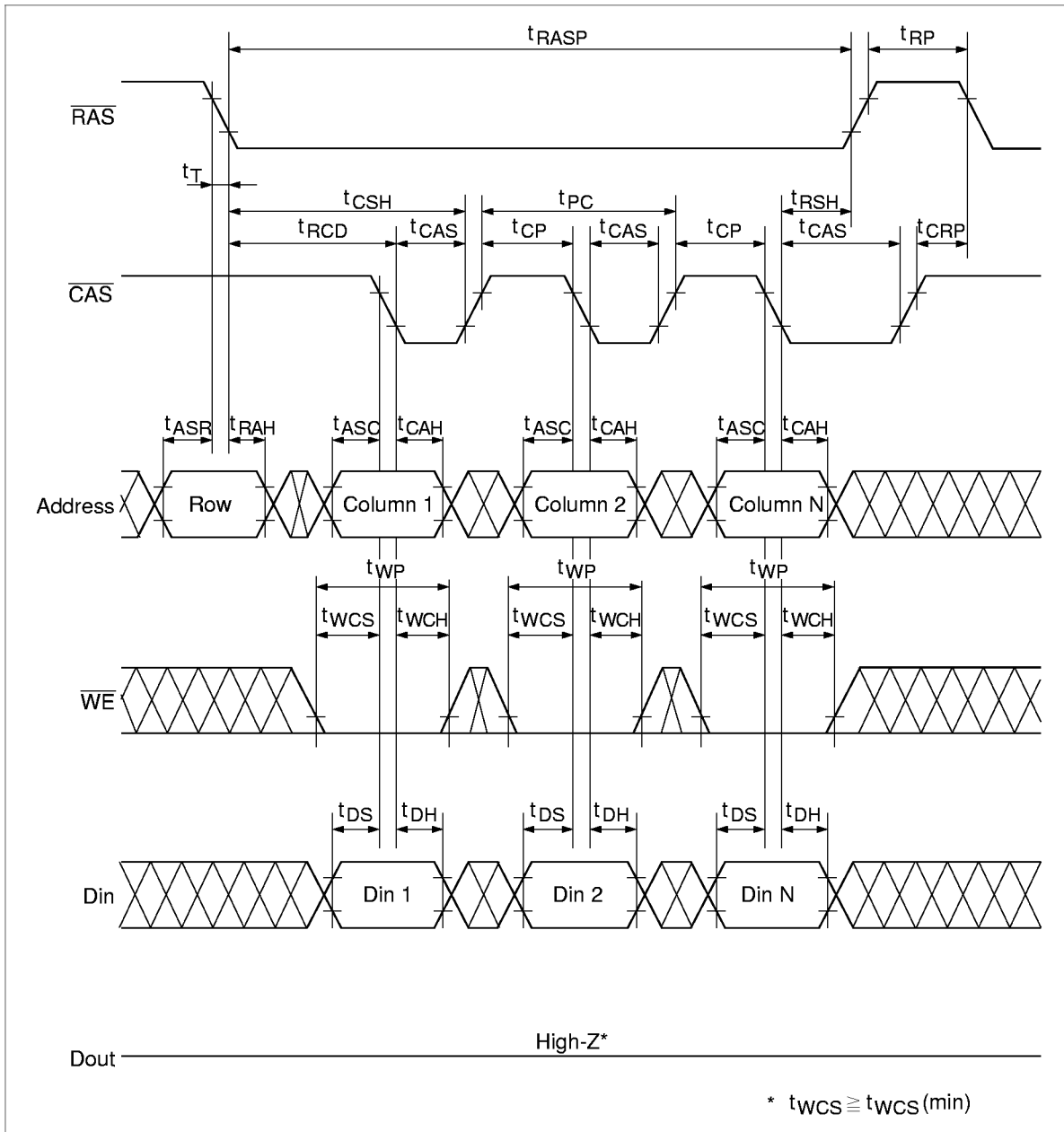


HB56G236 Series, HB56G136 Series

Fast Page Mode Read Cycle



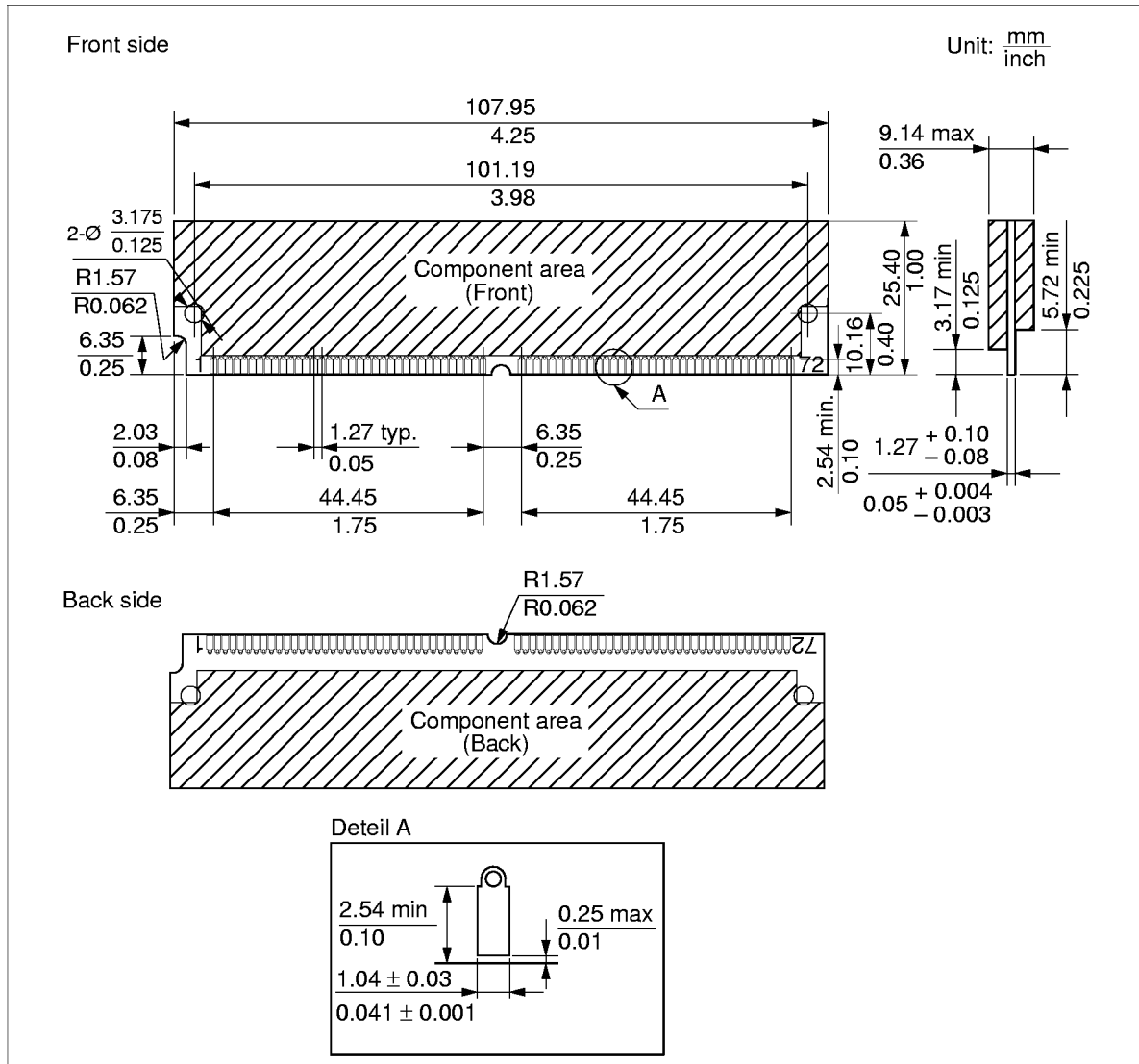
Fast Page Mode Early Write Cycle



HB56G236 Series, HB56G136 Series

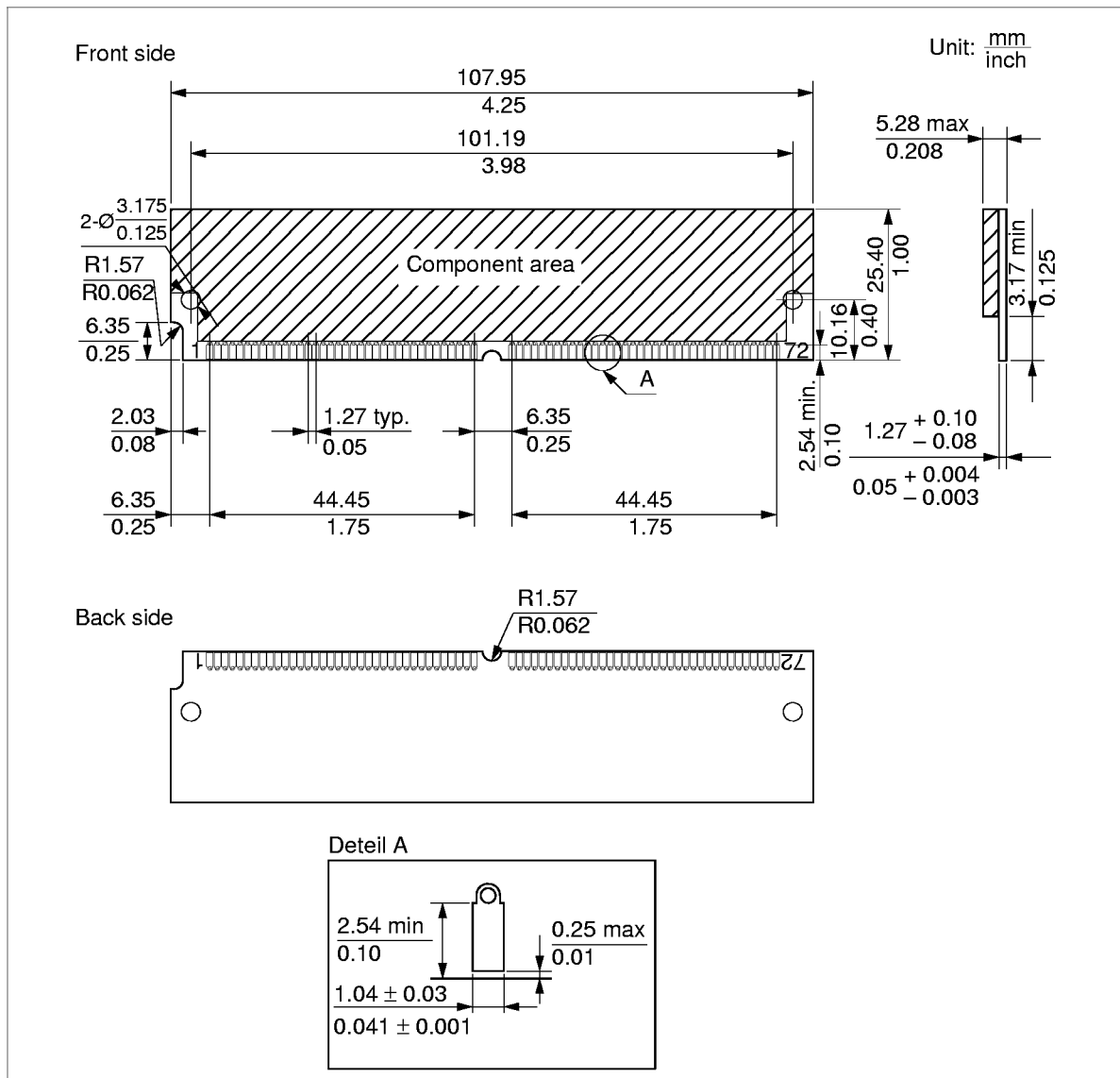
Physical Outline

HB56G236B/SB Series



HB56G236 Series, HB56G136 Series

HB56G136B/SB Series



HB56G236 Series, HB56G136 Series

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HB56G236 Series, HB56G136 Series

Revision Record

Rev.	Date	Contents of Modification	Drawn by	Approved by
1.0	Dec. 27, 1996	Initial issue	S. Tsukui	K. Tsuneda
2.0	Jun. 20, 1997	(referred to HM5116160/HM5118160 rev 3.0) DC Characteristics I_{CC7} Max : 520/ 460 mA to 510/ 450 mA (HB56G236) I_{CC7} Max : 500/ 440 mA to 490/ 430 mA (HB56G136)	S. Tsukui	K. Yoshizaki
3.0	Nov. 1997	Change of Subtitle		